

FEATURES

- Standalone USB PD sink controller
 - Support USB PD sink, up to 20 V / 5 A
 - Dead battery support
- Support QC2.0 12 V
- 4.5 V to 22 V operation range
- 25 V tolerance on VBUS, CC1, CC2 pins
- External resistor or capacitor to set the target RDO voltage
- Support SOP', eMarker emulator for cable application with output current > 3 A
- Power consumption 1.15 mA@5 V
- Package: DFN2x2-6L, SOT23-5L
- ± 2 kV HBM ESD Rating for USB IO pins

APPLICATIONS

- PD sink devices
- USB-C cables
- Wireless charger

GENERAL DESCRIPTION

The HUSB237 is a highly integrated USB Power Delivery (PD) controller as sink role for up to 100W power rating.

The HUSB237 integrates the CC logic, USB PD protocol and the legacy protocols, and it supports BC1.2 SDP, CDP and DCP, QC2.0.

The HUSB237 can be used in electronic devices that have legacy barrel connectors or USB micro-B connectors for power such as IoT (Internet of Things) devices, wireless charger, drones, smart speakers, power tools, and other rechargeable devices.

The HUSB237 is available in DFN2x2-6L or SOT23-5L package.

TYPICAL APPLICATION CIRCUIT

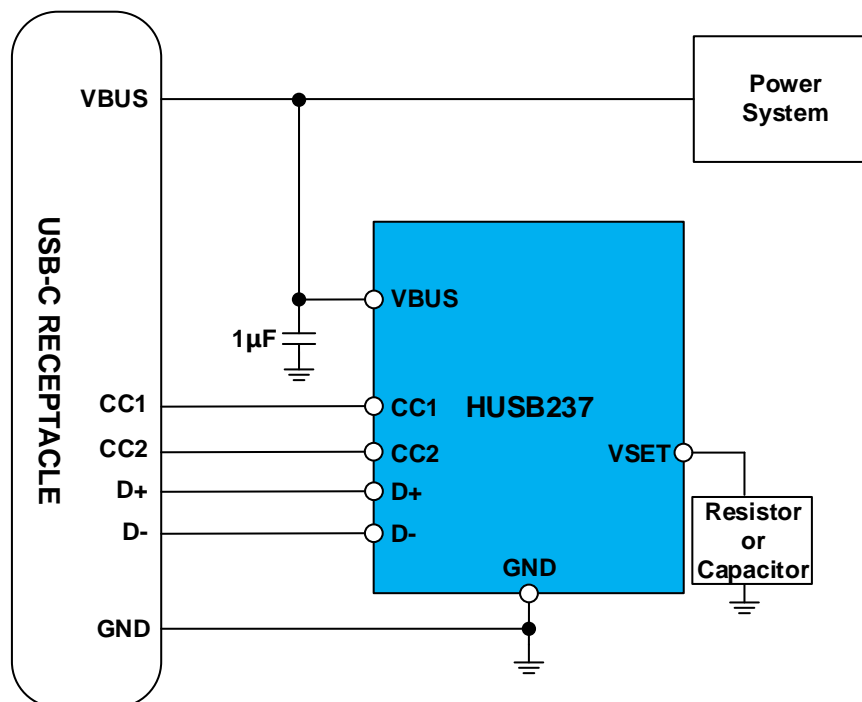


Figure 1. Typical Application Circuit

TABLE OF CONTENTS

Features	1
Applications	1
General Description	1
Typical Application Circuit	1
Table of Contents	2
Revision History	3
Pin Configuration and Function Descriptions	4
Recommended Operating Conditions	5
Specifications	5
Absolute Maximum Ratings	6
Thermal Resistance	6
ESD Caution	6
Functional Block Diagram	7
Theory of Operation	8
Overview	8
VBUS Pin	8
VSET Pin.....	8
Typical Application Circuits.....	9
Package Outline Dimensions	10
Package TOP Marking	12
Ordering Guide.....	13
Tape and Reel Information	14
Important Notice	15

REVISION HISTORY

Version	Date	Descriptions
Rev. 1.0	03/2024	Initial version

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

TOP VIEW

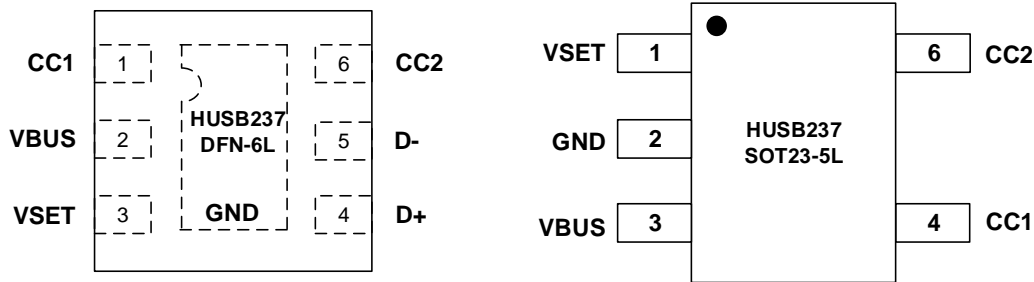


Figure 2. Pin Configuration

Table 1. DFN-6L Pin Function Descriptions

Pin No.	Pin Name	Type ¹	Description
1	CC1	AIO	Configuration line 1 used to negotiate a voltage/current with the attached adapter.
2	VBUS	P	Power supply input. Connect this pin to VBUS of USB Type-C connector and bias this pin via a 1 μ F ceramic capacitor.
3	VSET	AI	Connect a resistor or capacitor to indicate the maximum voltage needed by the system from the attached power adapter.
4	D+	DIO	Positive line of USB 2.0 data line for BC1.2.
5	D-	DIO	Negative line of USB 2.0 data line for BC1.2.
6	CC2	AIO	Configuration line 2 used to negotiate a voltage/current with the attached adapter.
7	GND	P	Ground reference. All signals are referred to this pin.

Table 2. SOT23-5L Pin Function Descriptions

Pin No.	Pin Name	Type ²	Description
1	VSET	AI	Connect a resistor or capacitor to indicate the maximum voltage needed by the system from the attached power adapter.
2	GND	P	Ground reference. All signals are referred to this pin.
3	VBUS	P	Power supply input. Connect this pin to VBUS of USB Type-C connector and bias this pin via a 1 μ F ceramic capacitor.
4	CC1	AIO	Configuration line 1 used to negotiate a voltage/current with the attached adapter.
5	CC2	AIO	Configuration line 2 used to negotiate a voltage/current with the attached adapter.

¹ Legend:

- A = Analog Pin
- P = Power Pin
- D = Digital Pin
- I = Input Pin
- O = Output Pin
- OD = Open Drain Pin

RECOMMENDED OPERATING CONDITIONS

Table 3.

Parameter	Rating
VBUS Input Voltage Range	3 V to 22 V
Operating Temperature Range (Junction)	-40 °C to +125 °C
Ambient Temperature Range	-40 °C to 85 °C

SPECIFICATIONS

VBUS = 5 V, T_A = 25 °C, unless otherwise noted.

Table 4.

Parameter	Symbol	Test Conditions/Comments	Min	Typ	Max	Unit
Power Supply						
VBUS UVLO Threshold	V _{BUS_UVLO_R}			3.78	4.2	V
	V _{BUS_UVLO_F}		3.3	3.65		V
VBUS Current	I _{VBUS}			1.15		mA
VSET						
Pull up Source Current	I _{SNK_VSET}	On VSET pin		20		μA
Detect Debounce Time	t _{DB_SNK_VSET}	For VSET pin		2		ms
SNK_VSET Setting Resistor or Capacitor	R _{SNK_VSET0}		0		100	Ω
	R _{SNK_VSET1}			75		kΩ
	R _{SNK_VSET2}			open		kΩ
	C _{SNK_VSET3}			4.7		nF
	C _{SNK_VSET4}			20		nF
Type-C Pins (CC1, CC2)						
Dead Battery Clamp Voltage	V _{SNKDB0}	with R _p =80 μA ±20% Current from Source	0.25		1.5	V
	V _{SNKDB1}	with R _p =180 μA ±8% Current from Source	0.45		1.5	V
	V _{SNKDB2}	with R _p =330 μA ±8% Current from Source	0.85		2.18	V
Sink Pull Down Resistor	R _d		4.6	5.1	5.6	kΩ
CC Impedance	Z _{OPEN}	CC1 or CC2 are disabled from R _d	1000			kΩ
R _a Detection Threshold	vR _{a_SNK}	Connected as Sink		0.2		V
R _d Detection Threshold	vR _{d_SNKDEF}	Connected as Sink with I _{RP_DEF} attached		0.66		V
	vR _{d_SNK1.5A}	Connected as Sink with I _{RP_1.5A} attached		1.23		V
CC Comparator Update Debounce	t _{CCUpdate}	Time for a CC Comparator to output a valid state change		2		ms
BC1.2 and HVDCP Detection						
BC1.2 Source voltage	V _{DPM_SRC_0V6}		0.5	0.6	0.7	V
BC1.2 Source Path Resistance	R _{DPM_SRC}	V _{DPM_SRC} =0.65V, from V _{DPM_SRC} to D+ and D- pin			65	Ω
BC1.2 Sink Current	I _{DPM_SNK}		50	100	150	μA
D+ Source Voltage for 3.3V	V _{DP_SRC_3P3}		3.0	3.3	3.6	V
D+ 3.3V Pull-up Resistance	R _{DP_SRC_3P3}		0.9	1.24	1.57	kΩ
Data Detect Voltage	V _{DAT_REF}		250	325	400	mV

ABSOLUTE MAXIMUM RATINGS

Table 5.

Parameter	Rating
VBUS, CC1, CC2	-0.3 V to +25 V
D+, D-, VSET	-0.3 V to +6 V
Operating Temperature Range (Junction)	-40 °C to +125 °C
Soldering Conditions	JEDEC J-STD-020
Electrostatic Discharge (ESD) Human Body Model (HBM)	±2000V

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

THERMAL RESISTANCE

Thermal performance is directly linked to printed circuit board (PCB) design and operating environment. Close attention to PCB thermal design is required.

θ_{JA} is the natural convection junction to ambient thermal resistance measured in a one cubic foot sealed enclosure.

θ_{JC} is the junction to case thermal resistance.

Table 6. Thermal Resistance

Package Type	θ_{JA}	θ_{JC}	Unit
DFN-6L	103.5	75.2	°C/W
SOT23-5L	221	140.5	°C/W

ESD CAUTION



Electrostatic Discharge Sensitive Device.

Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

FUNCTIONAL BLOCK DIAGRAM

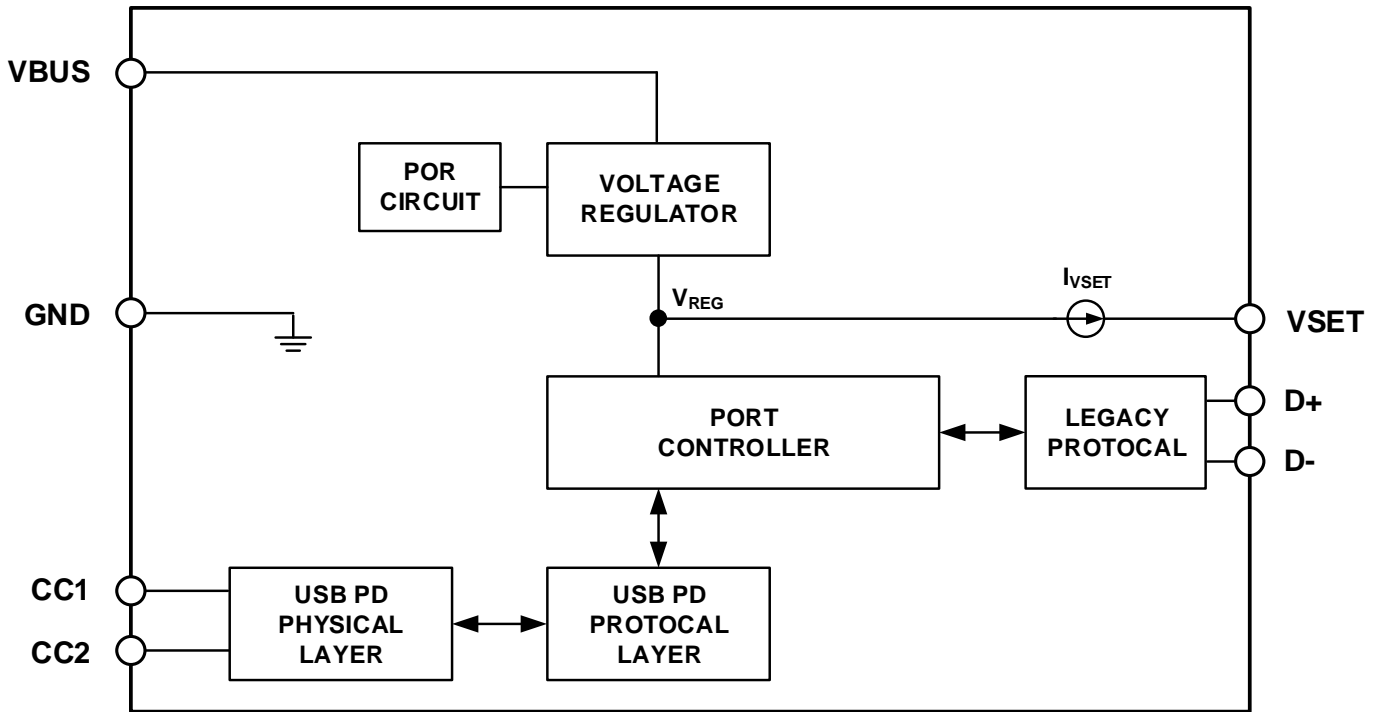


Figure 3. HUSB237 Functional Block Diagram

THEORY OF OPERATION

OVERVIEW

The HUSB237 is a highly integrated USB Power Delivery (PD) controller as sink role. It supports PD protocol and legacy charging protocols detection and requests the desired power per the user settings. When HUSB237 is connected to power source, it applies R_d to both CC lines, trying to establish USB Type-C connection. After the USB Type-C connection is established, it monitors the CC, DP and DM lines to determine corresponding charging protocol.

VBUS PIN

It is the input power source.

INPUT POWER SOURCE

VBUS pin is the power supply input of the HUSB237, which is derived from the output of the PD source. Connect a 1 μ F decoupling MLCC between VBUS pin and GND pin as close as possible.

VSET PIN

This pin is used to set the request voltage when the HUSB237 connected as a Sink. This pin is pulled up internally. Connect a resistor or capacitor with 1% tolerance between VSET and GND to indicate the target RDO voltage value as shown in Table 7.

Table 7. VSET Setting

VSET Pin Configuration	Preferred Voltage (V)
0 Ω	5
75 k Ω	9
open	12
4.7 nF	15
20 nF	20

The RDO voltage of the HUSB237 is determined by the VSET.

TYPICAL APPLICATION CIRCUITS

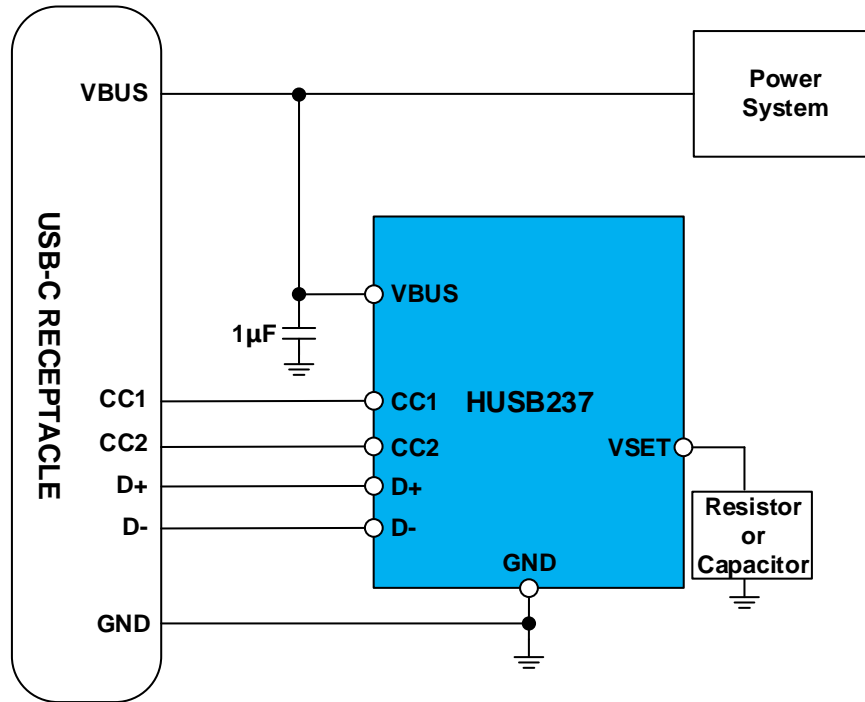
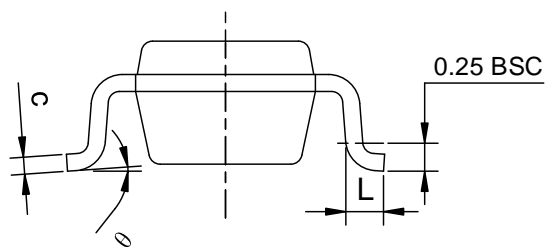
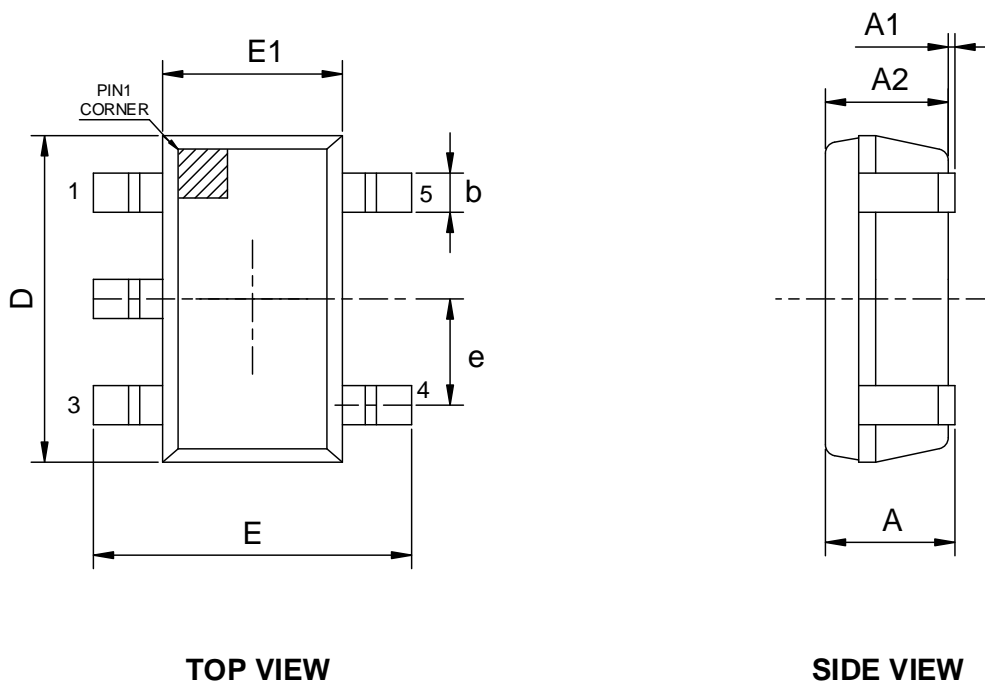


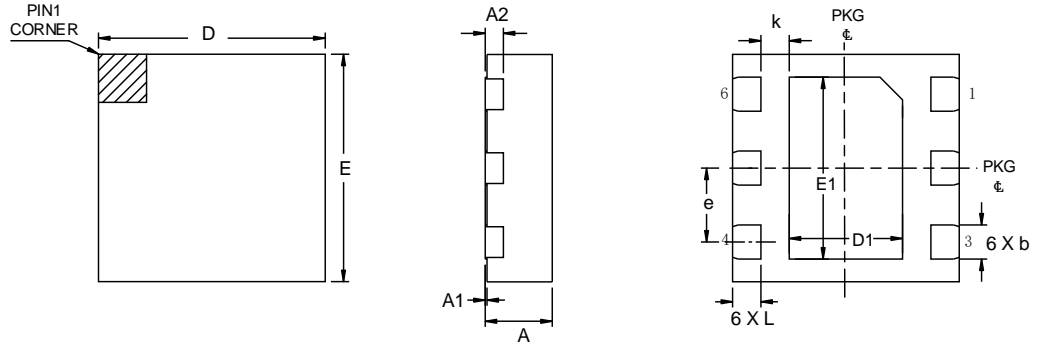
Figure 4. Typical Application Circuit

PACKAGE OUTLINE DIMENSIONS



SYMBOLS	DIMENSION IN MILLIMETERS		
	MIN	NOM	MAX
A	1.05	1.15	1.25
A1	0.00	0.06	0.10
A2	1.00	1.10	1.20
b	0.30	0.40	0.50
c	0.10	0.152	0.20
D	2.82	2.92	3.02
E	2.65	2.80	2.95
E1	1.50	1.61	1.70
e	0.95 BSC		
L	0.30	0.42	0.57
θ	0°	-	8°

Figure 5. SOT23-5L Package



TOP VIEW

SIDE VIEW

BOTTOM VIEW

SYMBOLS	DIMENSION IN MILLIMETERS		
	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A2	0.203 REF		
b	0.25	0.30	0.35
D	2.00 BSC		
E	2.00 BSC		
D1	0.63	1.00	1.10
E1	1.18	1.60	1.70
e	0.65 BSC		
L	0.20	0.25	0.35
k	0.15 MIN.		

Figure 6. 2 mm × 2 mm DFN-6L Package

PACKAGE TOP MARKING

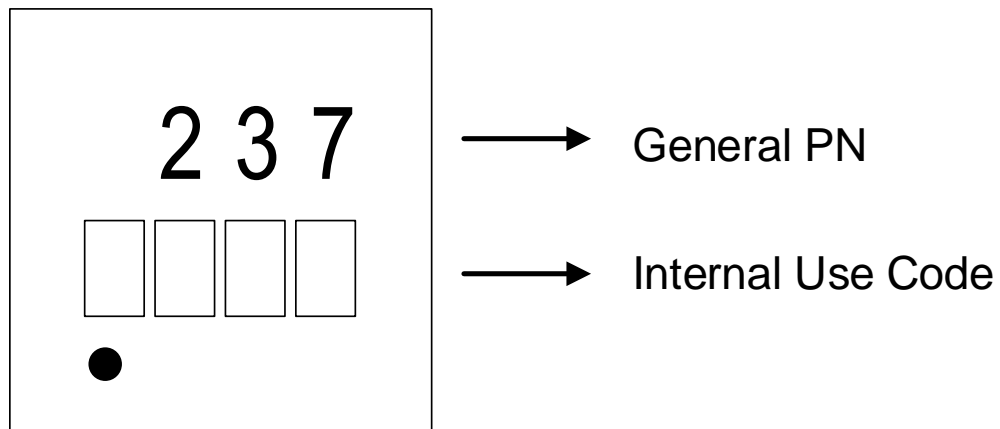
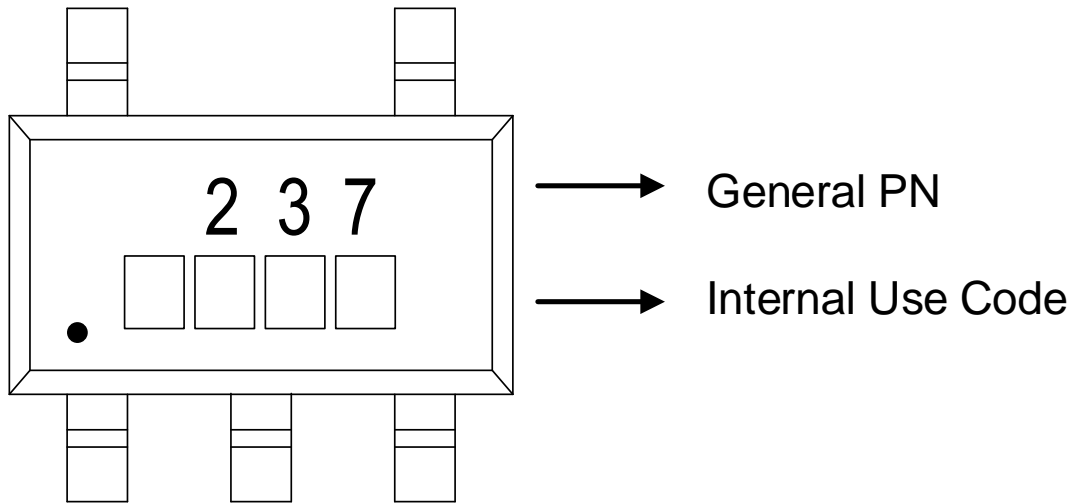
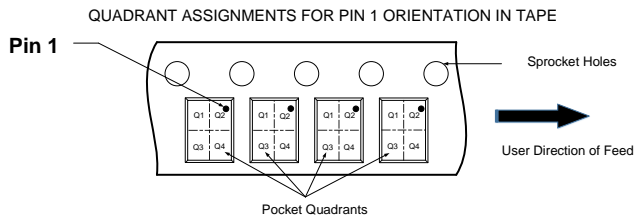
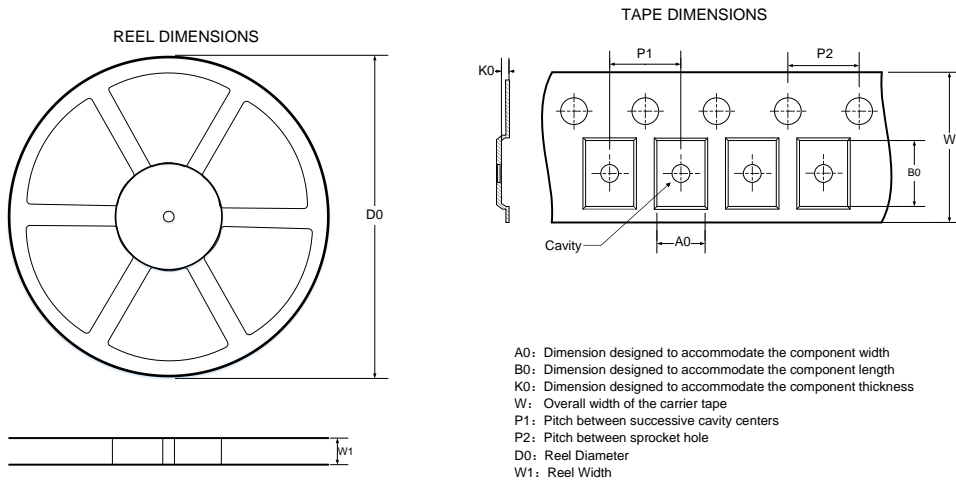


Figure 7. Package Top Marking

ORDERING GUIDE

Model	Temperature Range	Default Configuration	MSL	Package Option
HUSB237-AA001-DN06R	-40°C to 125°C	Support Sop'	MSL3	Tape & Reel, 4000
HUSB237-AB001-ST05R	-40°C to 125°C	Support Sop'	MSL3	Tape & Reel, 3000

TAPE AND REEL INFORMATION



DIMENSIONS AND PIN1 ORIENTATION

Device	Package Type	D0 (mm)	W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant	Quantity
HUSB237-AAXX-DN06R	DFN2X2-6L	178.00	9.50	2.30	2.30	1.10	4.00	4.00	8.00	Q2	4000
HUSB237-ABXX-ST05R	SOT23-5L	178.00	9.50	3.22	3.25	1.38	4.00	4.00	8.00	Q3	3000

All dimensions are nominal

Figure 8. Tape and Reel Information

IMPORTANT NOTICE

Hynetek Semiconductor Co., Ltd. and its subsidiaries (Hynetek) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to Hynetek's terms and conditions of sale supplied at the time of order acknowledgment.

Hynetek warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in Hynetek's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent Hynetek deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

Hynetek assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using Hynetek components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

Hynetek does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which Hynetek components or services are used. Information published by Hynetek regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from Hynetek under the patents or other intellectual property of Hynetek.

Reproduction of significant portions of Hynetek information in Hynetek data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Hynetek is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of Hynetek components or services with statements different from or beyond the parameters stated by Hynetek for that component or service voids all express and any implied warranties for the associated Hynetek component or service and is an unfair and deceptive business practice.

Hynetek is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of Hynetek components in its applications, notwithstanding any applications-related information or support that may be provided by Hynetek. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify Hynetek and its representatives against any damages arising out of the use of any Hynetek components in safety-critical applications.

In some cases, Hynetek components may be promoted specifically to facilitate safety-related applications. With such components, Hynetek's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No Hynetek components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those Hynetek components which Hynetek has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of Hynetek components which have not been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

Hynetek has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, Hynetek will not be responsible for any failure to meet ISO/TS16949.

Please refer to below URL for other products and solutions of Hynetek Semiconductor Co., Ltd.